

Attorney's Docket No. 042390P6126D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

8/Response  
NE  
P. Walker  
10-28-02

In re Application of:

Makarem A. Hussein

Serial No. 09/672,375

Filed: September 28, 2000

For: **A Process to Manufacture Continuous  
Metal Interconnects**

Examiner: Douglas W. Owens

Art Unit 2811

**RESPONSE TO FINAL OFFICE ACTION**

Box AF  
Assistant Commissioner for Patents  
Washington, D.C. 20231

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OCT 23 2002

TECHNOLOGY CENTER 2800

Dear Sir:

In response to the Final Office Action dated August 23, 2002, regarding the above-referenced application, Applicant respectfully requests consideration of the remarks that follow:

**REMARKS**

Claims 12-17 were examined and claims 12-17 stand rejected. Applicant respectfully requests reconsideration of pending claims 12-17 in view of at least the following remarks.

**I. Claims Rejected Under 35 U.S.C. §102**

The Patent Office rejects claims 12-17 under 35 U.S.C. 102(e) as being anticipated by U.S. Patent No. 6,323,131, issued to Obeng, et al ("Obeng"). The Patent Office states:

Regarding claim 12 and 16, Obeng et al. teaches an integrated circuit (FIG. 1(d)) comprising:

a substrate having a circuit device (22);

a dielectric material (10) over the circuit device with a via to the circuit device, wherein the via exposes a sidewall in the dielectric material and a surface of the circuit device;